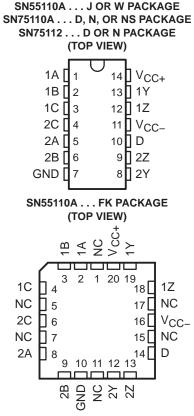
SLLS106G - DECEMBER 1975 - REVISED NOVEMBER 2004

- Improved Stability Over Supply Voltage and Temperature Ranges
- Constant-Current Outputs
- High Speed
- Standard Supply Voltages
- High Output Impedance
- High Common-Mode Output Voltage Range ...-3 V to 10 V
- TTL-Input Compatibility
- Inhibitor Available for Driver Selection
- Glitch Free During Power Up/Power Down
- SN75112 and External Circuit Meets or Exceeds the Requirements of CCITT Recommendation V.35

description/ordering information

The SN55110A, SN75110A, and SN75112 dual line drivers have improved output current regulation with supply-voltage and temperature variations. In addition, the higher current of the SN75112 (27 mA) allows data to be transmitted over longer lines. These drivers offer optimum performance when used with the SN55107A, SN75107A, and SN75108A line receivers.



NC - No internal connection

TA	PACKA	.GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		Tube of 05	SN75110AN	SN75110AN
	PDIP (N)	Tube of 25	SN75112N	SN75112N
0°C to 70°C		Tube of 50	SN75110AD	01754404
	SOIC (D)	Reel of 2500	SN75110ADR	SN75110A
		Tube of 50	SN75112D	0175440
		Reel of 2500	SN75112DR	SN75112
	SOP (NS)	Reel of 2000	SN75110ANSR	SN75110A
		Tube of 05	SN55110AJ	SN55110AJ
–55°C to 125°C	CDIP (J)	Tube of 25	SNJ55110AJ	SNJ55110AJ
-55 C 10 125 C	CFP (W)	Tube of 150	SNJ55110AW	SNJ55110AW
	LCCC (FK)	Tube of 55	SNJ55110AFK	SNJ55110AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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description/ordering information (continued)

These drivers feature independent channels with common voltage supply and ground terminals. The significant difference between the three drivers is in the output-current specification. The driver circuits feature a constant output current that is switched to either of two output terminals by the appropriate logic levels at the input terminals. The output current can be switched off (inhibited) by low logic levels on the enable inputs. The output current nominally is 12 mA for the '110A devices and is 27 mA for the SN75112.

The enable/inhibit feature is provided so the circuits can be used in party-line or data-bus applications. A strobe or inhibitor (enable D), common to both drivers, is included for increased driver-logic versatility. The output current in the inhibited mode, $I_{O(off)}$, is specified so that minimum line loading is induced when the driver is used in a party-line system with other drivers. The output impedance of the driver in the inhibited mode is very high. The output impedance of a transistor is biased to cutoff.

The driver outputs have a common-mode voltage range of -3 V to 10 V, allowing common-mode voltage on the line without affecting driver performance.

All inputs are diode clamped and are designed to satisfy TTL-system requirements. The inputs are tested at 2 V for high-logic-level input conditions and 0.8 V for low-logic-level input conditions. These tests ensure 400-mV noise margin when interfaced with TTL Series 54/74 devices.

The SN55110A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN75110A and SN75112 are characterized for operation from 0°C to 70°C.

	FUNCTION TABLE (each driver)										
LO			BLE UTS	OUTPUTS†							
Α	В	С	D	Y	Z						
Х	Х	L	Х	Off	Off						
Х	Х	Х	L	Off	Off						
L	Х	Н	Н	On	Off						
Х	L	Н	Н	On	Off						
Н	Н	Н	Н	Off	On						

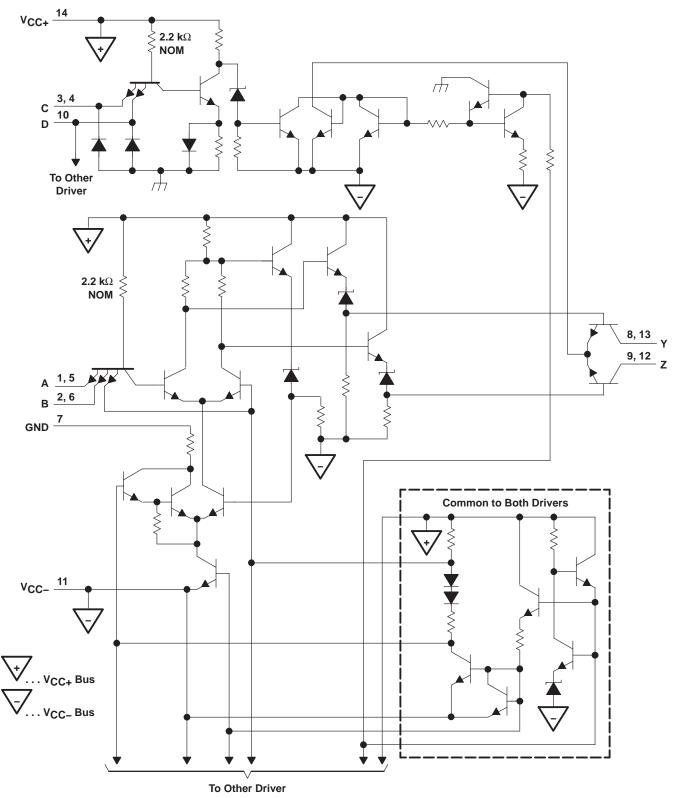
H = high level, L = low level, X = irrelevant

[†] When using only one channel of the line drivers, the other channel should be inhibited and/or have its outputs grounded.



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schematic (each driver)



Pin numbers shown are for the D, J, N, NS, and W packages.



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absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage: V _{CC+} (see Note 1) V _{CC-} (see Note 1)		
Input voltage, V_1		5.5 V
Output voltage range, VO		
Package thermal impedance, θ_{JA} (see Notes 2 and 3)		
	N package	80°C/W
	NS package	
Package thermal impedance, θ_{JC} (see Notes 4 and 5)	: FK package	13.42°C/W
	J package	15.05°C/W
	W package	14.65°C/W
Operating virtual junction temperature		150°C
Case temperature for 60 seconds: FK package		260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60		
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values are with respect to network ground terminal.

- 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.
- 4. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 5. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions (see Note 6)

		s	N55110A	A Contraction	SN75110A SN75112			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} +	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{CC} -	Supply voltage	-4.5	-5	-5.5	-4.75	-5	-5.25	V
	Positive common-mode output voltage	0		10	0		10	V
	Negative common-mode output voltage	0		-3	0		-3	V
VIH	High-level input voltage	2			2			V
VIL	Low-level output voltage			0.8			0.8	V
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 6: When using only one channel of the line drivers, the other channel should be inhibited and/or have its outputs grounded.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMET	ER	TEST CON	DITIONS [†]	-	N55110A		5	SN75112		UNIT			
					MIN	TYP‡	MAX	MIN	TYP‡	MAX				
VIK	Input clamp vo	oltage	$V_{CC\pm} = MIN,$	I _L = -12 mA		-0.9	-1.5		-0.9	-1.5	V			
			$V_{CC\pm} = MAX,$	V _O = 10 V		12	15		27	40				
I _{O(on)}	O(on) On-state output current		$V_{CC} = MIN \text{ to } N$ $V_{O} = -1 \text{ V to } 1 \text{ V}$					24	28	32	mA			
			$V_{CC\pm} = MIN,$	$V_{O} = -3 V$	6.5	12		15	27					
IO(off)	Off-state outp	ut current	$V_{CC\pm} = MIN,$	V _O = 10 V			100			100	μΑ			
	Input current	A, B, or C inputs					1			1				
II.	at maximum input voltage	D input	$V_{CC\pm} = MAX,$	V _I = 5.5 V			2			2	mA			
	High-level	A, B, or C inputs					40			40				
IН	input current	D input	$V_{CC\pm} = MAX,$	V _I = 2.4 V			80			80	μA			
	Low-level	A, B, or C inputs	$V_{CC\pm} = MAX, V_I = 0$	N 0.4 M			-3			-3				
۱	input current	D input		$v_{CC\pm} = MAX,$	$v_{CC\pm} = MAX,$	$v_{CC\pm} = iviAX,$	$v_{CC\pm} = MAX,$	$V_{I} = 0.4 V$			-6			-6
ICC+(on) Supply current from V _{CC} with driver enabled			$V_{CC\pm} = MAX$, A and B inputs a C and D inputs a	,		23	35		25	40	mA			
Supply current from V _{CC} – I _{CC} –(on) with driver enabled		$V_{CC\pm}$ = MAX, A and B inputs at 0.4 V, C and D inputs at 2 V			-34	-50		-65	-100	mA				
ICC+(off)	Supply curren with driver inh		$V_{CC\pm} = MAX,$ A, B, C, and D in	$V_{CC\pm} = MAX$, A, B, C, and D inputs at 0.4 V		21			30		mA			
I _{CC-(off)}	Supply curren with driver inh		$V_{CC\pm} = MAX,$ A, B, C, and D in	nputs at 0.4 V		-17			-32		mA			

[†] For conditions shown as MIN or MAX, use appropriate value specified under recommended operating conditions. [‡] All typical values are at $V_{CC+} = 5 V$, $V_{CC-} = -5 V$, $T_A = 25^{\circ}C$.

switching characteristics, V_{CC\pm} = ± 5 V, T_A = 25°C (see Figure 1)

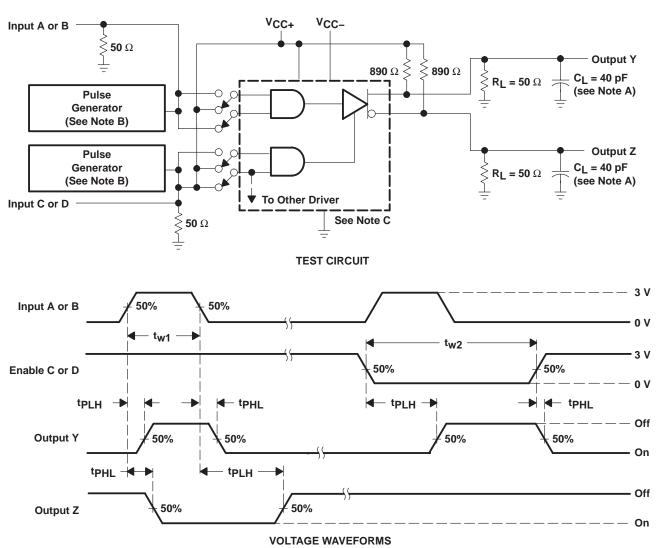
PARAMETER§	FROM (INPUT)	TO (OUTPUT)	TEST COM	NDITIONS	MIN	ТҮР	МАХ	UNIT
^t PLH	A an D	V or Z	0. 40 = 5	D. 50.0		9	15	
^t PHL	A or B	Y or Z	C _L = 40 pF,	R _L = 50 Ω,		9	15	ns
^t PLH	CorD	Y or Z	$C_{\rm L} = 40 \rm pE$	R ₁ = 50 Ω,		16	25	20
^t PHL	tPHL C or D	FOLZ	C _L = 40 pF,	KL = 50 32,		13	25	ns

 $\ensuremath{\$\xspace{1.5}\xs$

tpHL = propagation delay time, high- to low-level output



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. $\ensuremath{\mathsf{C}}_L$ includes probe and jig capacitance.

B. The pulse generators have the following characteristics: $Z_0 = 50 \ \Omega$, $t_r = t_f = 10 \pm 5 \text{ ns}$, $t_{W1} = 500 \text{ ns}$, PRR $\leq 1 \text{ MHz}$, $t_{W2} = 1 \ \mu\text{s}$, PRR $\leq 500 \text{ kHz}$.

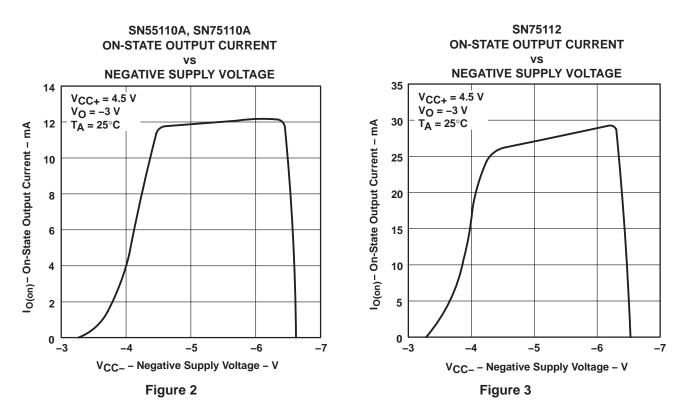
C. For simplicity, only one channel and the enable connections are shown.

Figure 1. Test Circuit and Voltage Waveforms



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TYPICAL CHARACTERISTICS





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APPLICATION INFORMATION

special pulse-control circuit

Figure 4 shows a circuit that can be used as a pulse-generator output or in many other testing applications.

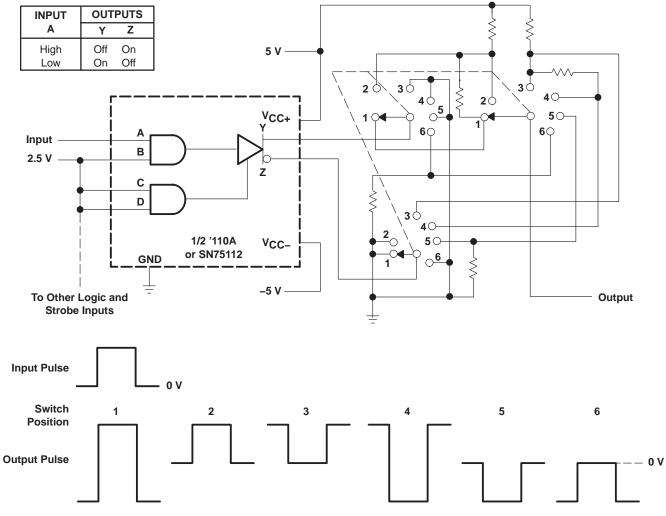


Figure 4. Pulse-Control Circuit



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APPLICATION INFORMATION

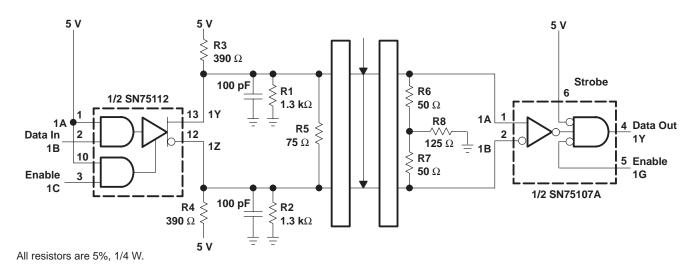
using the SN75112 as a CCITT-recommended V.35 line driver

The SN75112 dual line driver, the SN75107A dual line receiver, and some external resistors can be used to implement the data-interchange circuit of CCITT recommendation V.35 (1976) modem specification. The circuit of one channel is shown in Figure 5 and meets the requirement of the interface as specified by Appendix 11 of CCITT V.35 and is summarized in Table 1 (V.35 has been replaced by ITU V.11).

GENERATOR	MIN	MAX	UNIT
Source impedance, Z _{SOURCE}	50	150	Ω
Resistance to ground, R	135	165	Ω
Differential output voltage, VOD	440	660	mV
10% to 90% rise time, tr	40		ns
or		0.01 imesui†	
Common-mode output voltage, V_{OC}	-0.6	0.6	V
LOAD (RECEIVER)	MIN	MAX	UNIT
Input impedance, ZI	90	110	Ω
Resistance to ground, R	135	165	Ω

Table 1	CCITT	V 35	Flectrical	Rec	uirements
	COLLE	v.55	Electrical	reu	luirements

[†] ui = unit interval or minimum signal-element pulse duration









PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87547012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87547012A SNJ55 110AFK	Samples
5962-8754701CA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8754701CA SNJ55110AJ	Samples
5962-8754701DA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8754701DA SNJ55110AW	Samples
SN55110AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN55110AJ	Samples
SN75110AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75110A	Samples
SN75110ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75110A	Samples
SN75110AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75110AN	Samples
SN75110ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75110A	Samples
SN75112D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75112	Samples
SN75112DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75112	Samples
SN75112N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75112N	Samples
SNJ55110AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87547012A SNJ55 110AFK	Samples
SNJ55110AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8754701CA SNJ55110AJ	Samples
SNJ55110AW	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8754701DA SNJ55110AW	Samples

(1) The marketing status values are defined as follows:
 ACTIVE: Product device recommended for new designs.
 LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
 NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



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10-Jun-2022

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN55110A, SN75110A :

Catalog : SN75110A

Military : SN55110A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



Texas

*All dimensions are nominal

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75110ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75110ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75110ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75112DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

9-Aug-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75110ADR	SOIC	D	14	2500	340.5	336.1	32.0
SN75110ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN75110ANSR	SO	NS	14	2000	356.0	356.0	35.0
SN75112DR	SOIC	D	14	2500	356.0	356.0	35.0

TEXAS INSTRUMENTS

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9-Aug-2022

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-87547012A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-8754701DA	W	CFP	14	1	506.98	26.16	6220	NA
SN75110AD	D	SOIC	14	50	506.6	8	3940	4.32
SN75110AN	N	PDIP	14	25	506	13.97	11230	4.32
SN75110AN	N	PDIP	14	25	506	13.97	11230	4.32
SN75112D	D	SOIC	14	50	506.6	8	3940	4.32
SN75112N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ55110AFK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ55110AW	W	CFP	14	1	506.98	26.16	6220	NA

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



FK 20

8.89 x 8.89, 1.27 mm pitch

GENERIC PACKAGE VIEW

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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